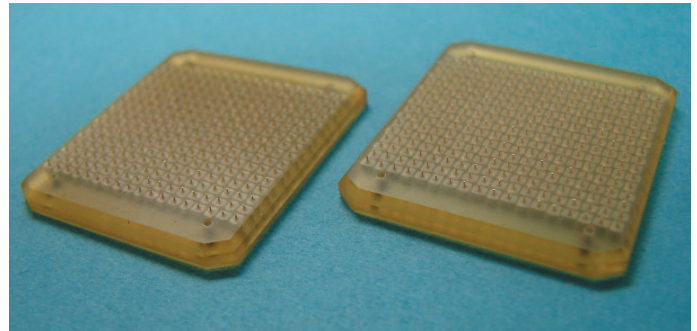


HyperGrid® Contact Technology

HyperGrid is a scalable interconnect technology that provides engineers with a high performance, robust “drop-in” replacement for pogo pin, elastomer-based and fuzz button connectors. Suitable for mezzanine level, IC-to-board, or board-to-board interconnect requirements, engineers can feel confident that HyperGrid contacts will replace any pogo pin or other discrete I/O compliant contact in interconnect environments constrained by space and weight limitations.

Based on a patented, Z axis compliant floating contact, HyperGrid provides an electrically-efficient connection, with a very consistent resistance value from pin to pin. The 0.50 to 1.27mm pitch contacts have a low self-inductance and use a repeatable, low contact force (0.35 - 1.59 oz.).

The technology delivers an interconnection that adheres to any standard and non-standard footprint and is easy to customize. HyperGrid is available in a number of connector and interposer products that can meet the most demanding requirements for signal integrity, reliability and performance. Suitable application areas include high speed microwave MMIC, flat panel displays, flexible cables, printed circuit board and parallel boards, and solderless, multiple-termination connectors for Mil/Aero avionics and various medical applications.



General Specifications	
Materials	Beryllium copper wire
Plating	Gold over nickel
Mechanical Specifications	
Pitch	0.5 - 1.27mm
Test Height	0.81 - 2.28mm
Full Travel	0.15 - 0.50mm
Recommended Travel	0.10 - 0.38mm
Overall Length	0.91 - 2.67mm
Contact Force	0.35 - 1.59 oz.
Electrical Specifications	
Current Rating	Up to 2.5 Amps
Self-inductance	Down to 0.5 nH
Character Impedance	56 ohms
< - 1 dB Bandwidth	Up to 37 GHz
DC Resistance	< 50 milliohms

Features and Benefits

- Compliant contact provides high reliability with space and weight savings
- Discrete nodes, all metal, no elastomers
- Low contact self inductance
- Consistent resistance across nodes
- Minimum of 100,000 mating cycles
- Scalable interconnect by pitch
- Customizable footprint
- Superior signal integrity
- Known discrete-node resistance-measurements
- Known repeatable force-deflection characteristics

